

FEATURES

- Function, Pinout and Drive Compatible with the FCT, F and AM29841 Logic
- FCT-C speed at 5.5ns max. (Com'l)
FCT-B speed at 6.5ns max. (Com'l)
- Reduced V_{OH} (typically = 3.3V) versions of Equivalent FCT functions
- Edge-rate Control Circuitry for Significantly Improved Noise Characteristics
- Power-off disable feature
- Matched Rise and Fall times
- Fully Compatible with TTL Input and Output Logic Levels
- 64 mA Sink Current (Com'l), 32 mA (Mil)
15 mA Source Current (Com'l), 12 mA (Mil)
- Buffered Common Clear and Preset Input
- High Speed Parallel Latches
- Buffered Common Latch Enable Input

2

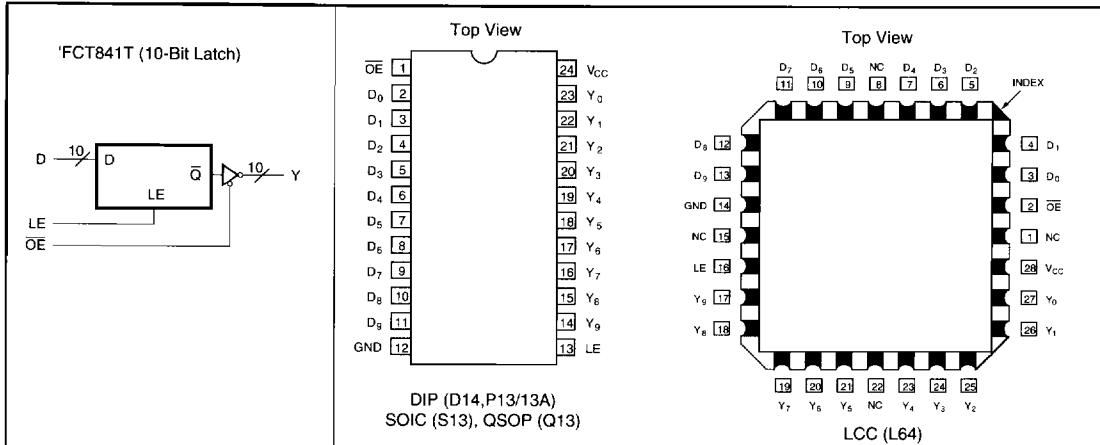
DESCRIPTION

The 'FCT841T series bus interface latches are designed to eliminate the extra packages required to buffer existing latches and provide extra data width for wider address/data paths or buses carrying parity. The 'FCT841T is a buffered 10-bit wide version of the 'FCT373 function.

The 'FCT841T high performance interface family is designed for high-capacitance load drive capability while providing low-capacitance bus loading at both inputs and outputs. All inputs have clamp diodes and all outputs are designed for low-capacitance bus loading in the high impedance state.

LOGIC SYMBOLS

PIN CONFIGURATONS



PIN DESCRIPTION

Name	I/O	Description
D ₁	I	The latch data inputs.
LE	I	The latch enable input. The latches are transparent when LE is HIGH. Input data is latched on the HIGH-to-LOW transition.
Y ₁	O	The three-state latch outputs.
OE	I	The output enable control. When OE is LOW, the outputs are enabled. When OE is HIGH, the outputs Y ₁ are in the high-impedance (off) state.

1719 Tbl 01

FUNCTION TABLES §

'FCT841T

Inputs			Internal	Outputs	Function
OE	LE	D ₁	O ₁	Y ₁	
H	X	X	X	Z	High Z
H	H	L	L	Z	High Z
H	H	H	H	Z	HighZ
H	L	X	NC	Z	Latched (High Z)
L	H	L	L	L	Transparent
L	H	H	H	H	Transparent
L	L	X	NC	NC	Latched

§ H = HIGH, L = LOW, X = Don't care, NC = No Change, Z = High Impedance.

1719 Tbl 02

ABSOLUTE MAXIMUM RATINGS^{1,2}

Symbol	Parameter	Value	Unit
T _{STG}	Storage Temperature	-65 to +150	°C
T _A	Ambient Temperature Under Bias	-65 to +135	°C
V _{CC}	V _{CC} Potential to Ground	-0.5 to +7.0	V
P _T	Power Dissipation	0.5	W

1719 Tbl 03

Notes:

1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

Symbol	Parameter	Value	Unit
I _{OUTPUT}	Current Applied to Output	120	mA
V _{IN}	Input Voltage	-0.5 to +7.0	V
V _{OUT}	Voltage Applied to Output	-0.5 to +7.0	V

1719 Tbl 04

2

RECOMMENDED OPERATING CONDITIONS

Free Air Ambient Temperature	Min	Max
Military	-55°C	+125°C
Commercial	0°C	+70°C

1719 Tbl 05

Supply Voltage (V _{CC})	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

1719 Tbl 06

DC ELECTRICAL CHARACTERISTICS (Over recommended operating conditions)

Symbol	Parameter		Min	Typ ¹	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage		2.0			V		
V _{IL}	Input LOW Voltage				0.8	V		
V _H	Hysteresis			0.2		V		All inputs
V _{IK}	Input Clamp Diode Voltage			-0.7	-1.2	V	MIN	I _{IN} = -18mA
V _{OH}	Output HIGH Voltage	Military	2.4	3.3		V	MIN	I _{OH} = -12mA
		Commercial	2.4	3.3		V	MIN	I _{OH} = -15mA
V _{OL}	Output LOW Voltage	Military		0.3	0.5	V	MIN	I _{OL} = 32mA
		Commercial		0.3	0.5	V	MIN	I _{OL} = 48mA
		Commercial		0.3	0.5	V	MIN	I _{OL} = 64mA
I _I	Input HIGH Current				20	µA	MAX	V _{IN} = V _{CC}
I _{IH}	Input HIGH Current				5	µA	MAX	V _{IN} = 2.7V
I _{IL}	Input LOW Current				-5	µA	MAX	V _{IN} = 0.5V
I _{OZH}	Off State I _{OUT} HIGH-Level Output Current				10	µA	MAX	V _{OUT} = 2.7V
I _{OZL}	Off State I _{OUT} LOW-Level Output Current				-10	µA	MAX	V _{OUT} = 0.5V
I _{OS}	Output Short Circuit Current ²		-60	-120	-225	mA	MAX	V _{OUT} = 0.0V
I _{OFF}	Power-off Disable				100	µA	0V	V _{OUT} = 4.5V
C _{IN}	Input Capacitance ³			5	10	pF	MAX	All inputs
C _{OUT}	Output Capacitance ³			9	12	pF	MAX	All outputs
I _{CC}	Quiescent Power Supply Current			0.2	1.5	mA	MAX	V _{IN} ≤ 0.2V, V _{IN} ≥ V _{CC} - 0.2V

1719 Tbl 07

Notes:

1. Typical values are at V_{CC} = 3.3V, T_A = +25°C ambient.
2. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in

order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

3. This parameter is guaranteed but not tested.

DC CHARACTERISTICS (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ ¹	Max	Units	Conditions
ΔI_{CC}	Quiescent Power Supply Current (TTL inputs) ²	0.5	2.0	mA	$V_{CC} = MAX, V_{IN} = 2.7V^2, f_i = 0, Outputs Open$
I_{CCD}	Dynamic Power Supply Current ³	0.15	0.25	mA/MHz	$V_{CC} = MAX, One Input Toggling, 50\% Duty Cycle, Outputs Open, OE = GND, LE = V_{CC}, V_{IN} \leq 0.2V \text{ or } V_{IN} \geq V_{CC} - 0.2V$
I_C	Total Power Supply Current ⁵	1.7	4.0	mA	$V_{CC} = MAX, 50\% Duty Cycle, Outputs Open, One Bit Toggling at fi = 10MHz, OE = GND, LE = V_{CC}, V_{IN} \leq 0.2V \text{ or } V_{IN} \geq V_{CC} - 0.2V$
		2.0	5.0	mA	$V_{CC} = MAX, 50\% Duty Cycle, Outputs Open, One Bit Toggling at fi = 10MHz, OE = GND, LE = V_{CC}, V_{IN} = 3.4V \text{ or } V_{IN} = GND$
		3.2	6.5 ⁴	mA	$V_{CC} = MAX, 50\% Duty Cycle, Outputs Open, Eight Bits Toggling at fi = 2.5MHz, OE = GND, LE = V_{CC}, V_{IN} \leq 0.2V \text{ or } V_{IN} \geq V_{CC} - 0.2V$
		5.2	14.5 ⁴	mA	$V_{CC} = MAX, 50\% Duty Cycle, Outputs Open, Eight Bits Toggling at fi = 2.5MHz, OE = GND, LE = V_{CC}, V_{IN} = 3.4V \text{ or } V_{IN} = GND$

Notes:

1. Typical values are at $V_{CC} = 3.3V$, +25°C ambient.
2. Per TTL driven input ($V_{IN} = 2.7V$); all other inputs at V_{CC} or GND.
3. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
4. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
5. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_d/2 + f_i N_i)$
 $I_{CC} =$ Quiescent Current with CMOS input levels
 $\Delta I_{CC} =$ Power Supply Current for a TTL High Input ($V_{IN} = 2.7V$)

1719 Tbl 08

- D_H = Duty Cycle for TTL Inputs High
 N_T = Number of TTL Inputs at D_H
 I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
 f_0 = Clock Frequency for Register Devices (Zero for Non-Register Devices)
 f_i = Input Frequency
 N_i = Number of Inputs at f_i
 All currents are in millamps and all frequencies are in megahertz.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE

Sym.	Parameter	Test Conditions ^{1,*}	'FCT841AT				'FCT841BT				'FCT841CT				Units	
			MIL		COM'L		MIL		COM'L		MIL		COM'L			
			Min. ²	Max.												
t_{PLH} t_{PHL}	Propagation Delay D_i to Y_i (LE = HIGH)	$C_L = 50\text{pF}$ $R_L = 500\Omega$		10.0		9.0		7.5		6.5		6.3		5.5	ns	
		$C_L = 300\text{pF}^3$ $R_L = 500\Omega$		15.0		13.0		15.0		13.0		15.0		13.0	ns	
t_{SU}	Data to LE Set-up Time	$C_L = 50\text{pF}$	2.5		2.5		2.5		2.5		2.5		2.5		ns	
t_H	Data to LE Hold Time	$R_L = 500\Omega$	3.0		2.5		2.5		2.5		2.5		2.5		ns	
t_{PLH} t_{PHL}	Propagation Delay LE to Y_i	$C_L = 50\text{pF}$ $R_L = 500\Omega$		13.0		12.0		10.5		8.0		6.8		6.4	ns	
		$C_L = 300\text{pF}^3$ $R_L = 500\Omega$		20.0		16.0		18.0		15.5		16.0		15.0	ns	
t_{PZH} t_{PZL}	Output Enable Time \overline{OE} to Y_i	$C_L = 50\text{pF}$ $R_L = 500\Omega$		13.0		11.5		8.5		8.0		7.3		6.5	ns	
		$C_L = 300\text{pF}^3$ $R_L = 500\Omega$		25.0		23.0		15.0		14.0		13.0		12.0	ns	
t_{PLZ} t_{PZL}	Output Disable Time \overline{OE} to Y_i	$C_L = 5\text{pF}^3$ $R_L = 500\Omega$		9.0		7.0		6.5		6.0		6.0		5.7	ns	
		$C_L = 50\text{pF}$ $R_L = 500\Omega$		10.0		8.0		7.5		7.0		6.3		6.0	ns	

Notes:

1. See test circuit and waveforms.
 2. Minimum limits are guaranteed but not tested on Propagation Delays.
 3. This parameters are guaranteed but not tested.
- * See "Parameter Measurement Information" in the General Information Section.

1719 Tbl 09

ORDERING INFORMATION

CYxxFCT	xxxx	x	x	
Temp. Range	Device Type	Package	Process	
				C Commercial
				M Military
				MB MIL-STD-883, Class B
				P Plastic DIP
				D CERDIP
				SO Small Outline IC
				L Leadless Chip Carrier
				Q QSOP
			841AT	10-Bit Non-inverting Latch
			841BT	Fast 10-Bit Non-inverting Latch
			841CT	Ultra Fast 10-Bit Non-inverting Latch
			74	Commercial
			54	Military